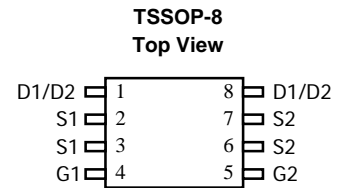


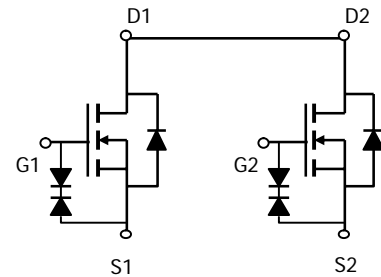
Dual N-Channl Enhancement Mode MOSFET

- 20V/7.5A
- $R_{DS(ON)}=14m\Omega$ (typ) @VGS=4.5V
 $R_{DS(ON)}=18m\Omega$ (typ) @VGS=2.5V
- 100% UIS & RG Tested
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)



Applications

- Power Management for Industrial DC/DC Converters



Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Unit	
Common Ratings				
V_{DSS}	Drain-Source Voltage	20	V	
V_{GSS}	Gate-Source Voltage	± 12		
I_D	Continuous Drain Current ^A	$T_A=25^\circ\text{C}$	7.5	A
		$T_A=70^\circ\text{C}$	6	
I_{DM}	Pulsed Drain Current ^B	$T_c=25^\circ\text{C}$	30	A
T_{STG}, T_j	Storage Temperature Range	-55 to 150	$^\circ\text{C}$	
PD	Power Dissipation ^A	$T_A=25^\circ\text{C}$	1.5	W
		$T_A=70^\circ\text{C}$	1	
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	$t \leq 10\text{S}$	64	$^\circ\text{C/W}$
		Steady-State	89	
$R_{\theta JC}$	Thermal Resistance-Junction to Case ^C	53	$^\circ\text{C/W}$	

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress rating only and functional device operation is not implied

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C: The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

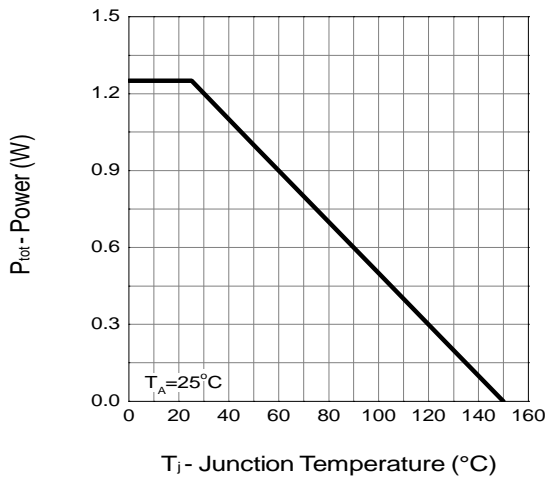
Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 16V, V_{GS}=0V$	-	-	1	μA
		$T_J=55^\circ\text{C}$	-	-	5	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{DS}=250\mu A$	0.4	0.6	1	V
$I_{D(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=4.5V, V_{DS}=5V$	30			A
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 4.5V, V_{DS}=0V$	-	-	± 1	μA
		$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	± 10	
$R_{DS(ON)}$	Drain-Source On-state Resistance	$V_{GS}=4.5V, I_{D}=7A$	10	14	19	$m\Omega$
		$T_J=125^\circ\text{C}$	16	20	25	
		$V_{GS}=4V, I_D=7A$	11	15.5	19	
		$V_{GS}=3.1V, I_D=6.5A$	12	16	20	
		$V_{GS}=2.5V, I_D=5.5A$	13	18	22	
		$V_{GS}=1.8V, I_D=5A$	14	20	28	
g_{FS}	Forward Transconductance	$V_{DS}=5V, I_D=7A$	-	31	-	S
I_s	Maximum Body-Diode Continuous Current		-	-	2.5	A
Body Diode Characteristics						
V_{SD}	Diode Forward Voltage	$I_{SD}=1A, V_{GS}=0V$	-	0.7	1.3	V
t_{rr}	Reverse Recovery Time	$I_{DS}=7A$	-	32	-	ns
Q_{rr}	Reverse Recovery Charge	$di_{SD}/dt=100A/\mu s$	-	12	-	nC
Dynamic Characteristics						
R_G	Gate Resistance	$F=1\text{MHz}$, Open drain	-	4	-	Ω
C_{ISS}	Input Capacitance	$V_{GS}=0V, V_{DS} = 10V,$ Frequency=1.0MHz	-	1120	-	pF
C_{OSS}	Output Capacitance		-	195	-	
C_{RSS}	Reverse transfer capacitance		-	155	-	
$t_{d(ON)}$	Turn-on delay Time	$V_{GS}=5V, V_{DS}=10V$ $R_G=3\Omega, R_L=1.35\Omega,$	-	7.2	-	nS
t_r	Turn-on rise Time		-	11	-	
$t_{d(OFF)}$	Turn-off delay Time		-	64	-	
t_f	Turn-off rise Time		-	32	-	
Gate Charge Characteristics						
Q_g	Total Gate Charge	$V_{DS} = 10V, V_{GS}=4.5V,$ $I_{DS}=7A$	-	16	-	nC
Q_{gs}	Gate-Source Charge		-	1.7	-	
Q_{gd}	Gate-Drain Charge		-	6.8	-	

Note: 1. Pulse test: pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

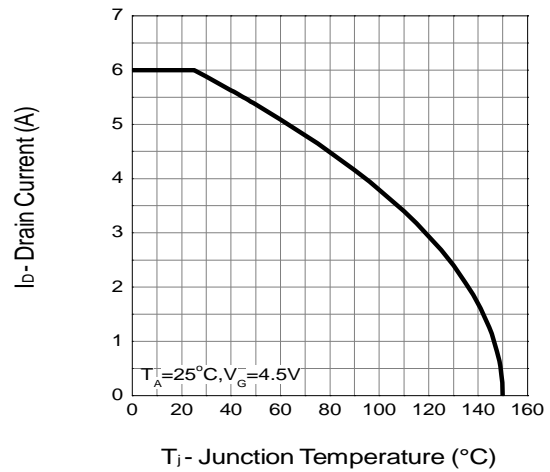
2.Static parameters are based on package level with recommended wire bonding

TYPICAL CHARACTERISTICS (25°C Unless Note)

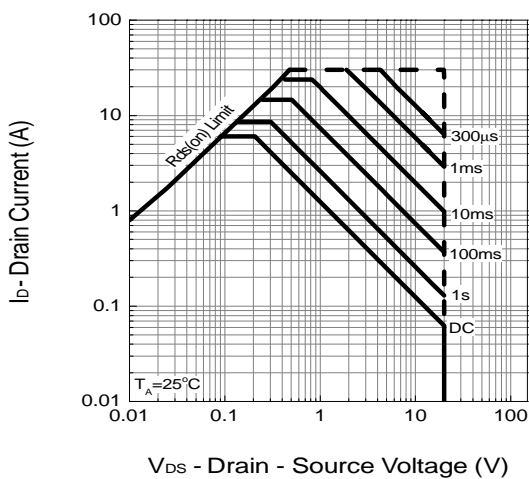
Power Dissipation



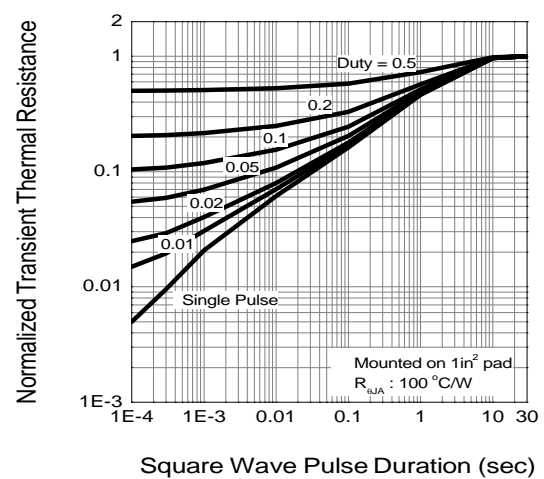
Drain Current



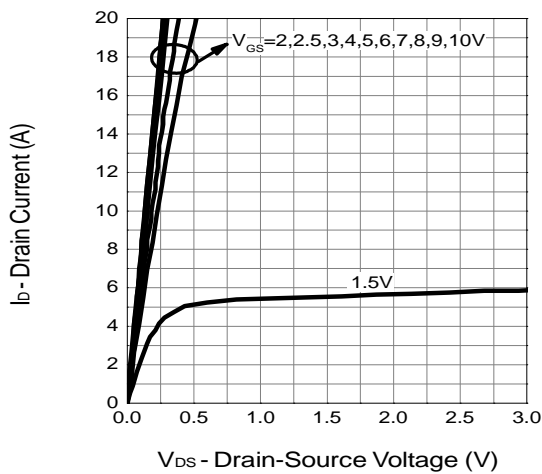
Safe Operation Area



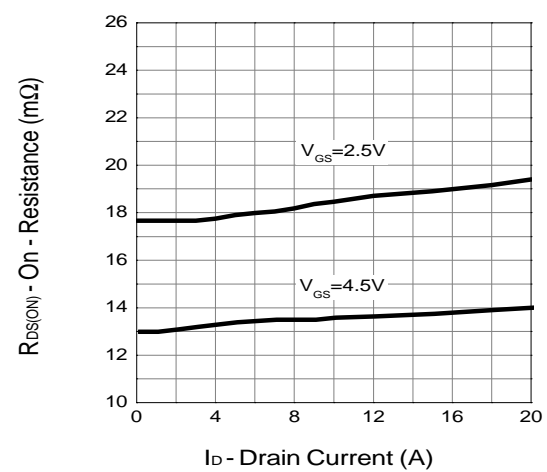
Thermal Transient Impedance



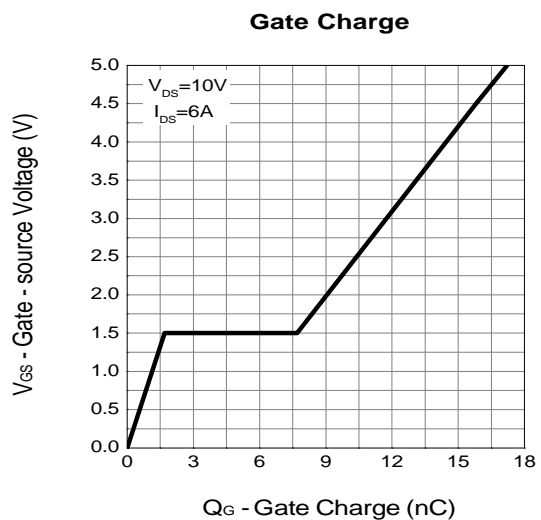
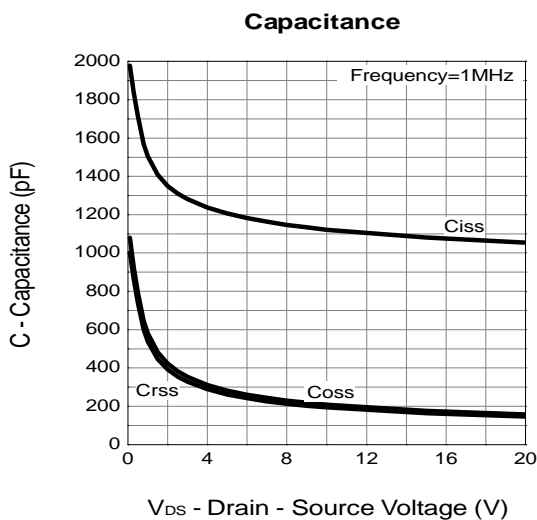
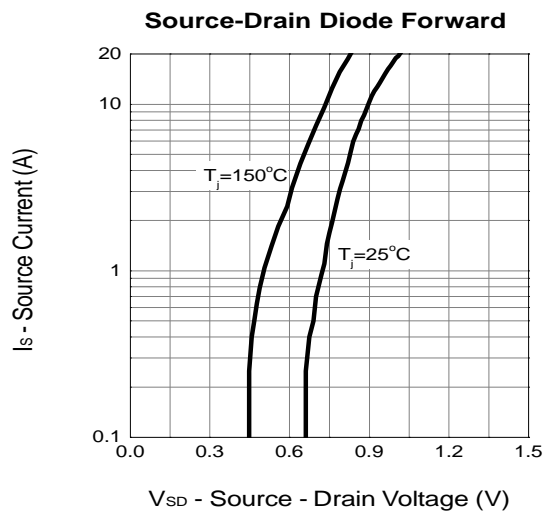
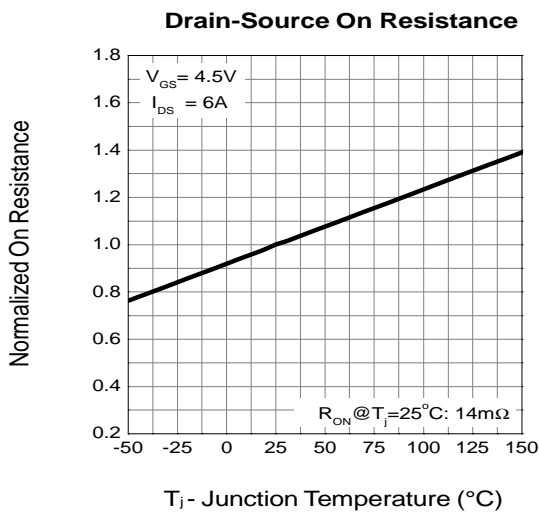
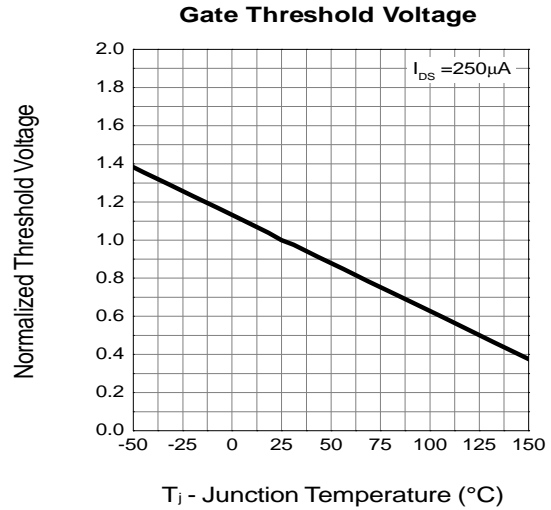
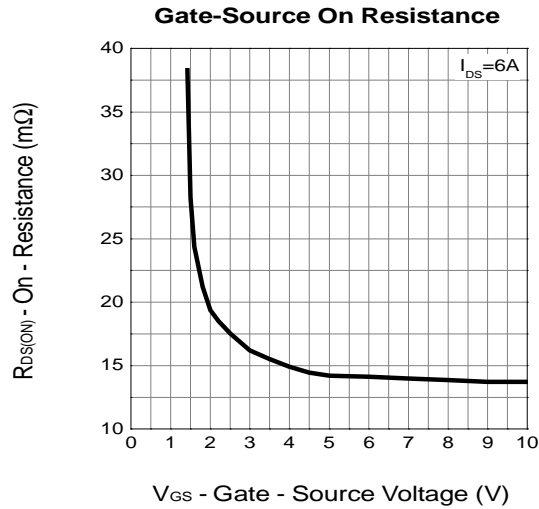
Output Characteristics



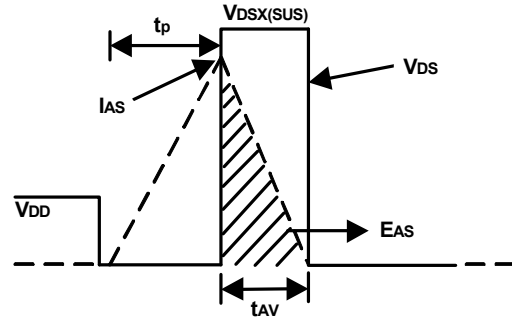
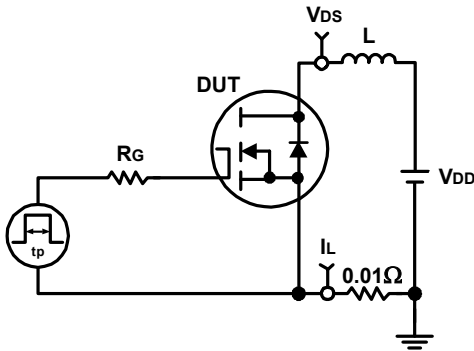
Drain-Source On Resistance



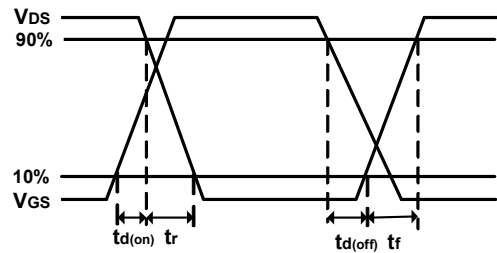
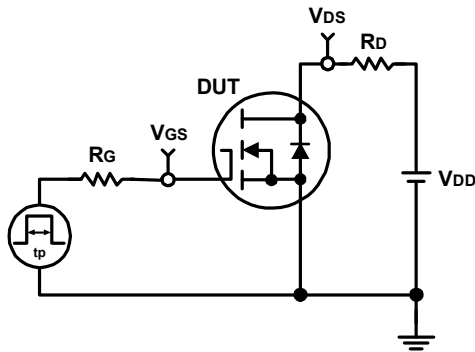
TYPICAL CHARACTERISTICS (continuous)



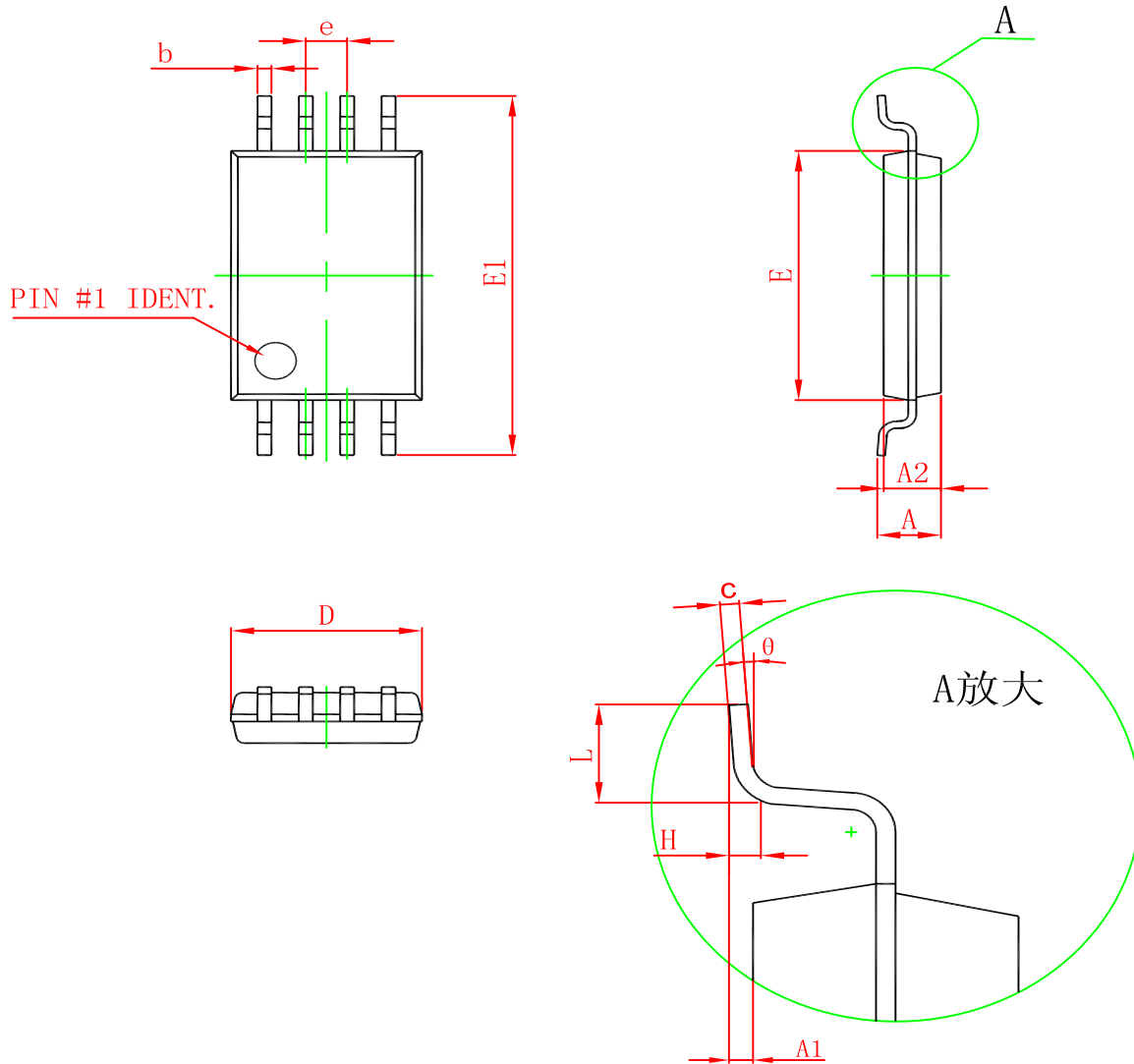
Avalanche Test Circuit and Waveforms



Switching Time Test Circuit and Waveforms



TSSOP8L PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
D	2.900	3.100	0.114	0.122
E	4.300	4.500	0.169	0.177
b	0.190	0.300	0.007	0.012
c	0.090	0.200	0.004	0.008
E1	6.250	6.550	0.246	0.258
A		1.100		0.043
A2	0.800	1.000	0.031	0.039
A1	0.020	0.150	0.001	0.006
e	0.65 (BSC)		0.026 (BSC)	
L	0.500	0.700	0.020	0.028
H	0.25 (TYP)		0.01 (TYP)	
θ	1°	7°	1°	7°